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REVISION HISTORY

2/2019—Revision 0: Initial Version

SPECIFICATIONS

All voltages are relative to their respective ground. 4.5 V ≤ V_{CC} ≤ 5.5 V, 1.7 V ≤ V_{IO} ≤ 5.5 V, −55°C ≤ T_A ≤ +105°C, and STBY low, unless otherwise noted. Typical specifications are at V_{CC} = V_{IO} = 5 V and T_A = 25°C, unless otherwise noted.

Table 1.

Parameter	Symbol	Min	Typ	Max	Unit	Test Conditions/Comments
SUPPLY CURRENT						
Logic Side *iso*Power Current	I_{CC}					
Standby			13.5	30	mA	STBY high, AUX_{IN} low, load resistance (R_L) = 60 Ω
Recessive State (or Silent)			27	40	mA	TXD and/or SILENT high, R_L = 60 Ω
Dominant State			180	260	mA	Fault condition, R_L = 60 Ω
70% Dominant/30% Recessive						Worst case, R_L = 60 Ω
1 Mbps			138		mA	
5 Mbps			151	200	mA	
12 Mbps			177	220	mA	
Switching Frequency	f_{OSC}		180		MHz	Frequency hopping center
Logic Side *i*Coupler Current	I_{IO}					
Normal Mode			3.6	5	mA	TXD high, low or switching, AUX_{IN} low
Standby Mode			1.2	2	mA	STBY high
DRIVER						
Differential Outputs						See Figure 27
Recessive State, Normal Mode						TXD high, R_L and common-mode filter capacitor (C_F) open
CANH, CANL Voltage	V_{CANL}, V_{CANH}	2.0		3.0	V	
Differential Output Voltage	V_{OD}	−500		+50	mV	
Dominant State, Normal Mode						TXD and SILENT low, C_F open
CANH Voltage	V_{CANH}	2.75		4.5	V	50 Ω ≤ R_L ≤ 65 Ω
CANL Voltage	V_{CANL}	0.5		2.0	V	50 Ω ≤ R_L ≤ 65 Ω
Differential Output Voltage	V_{OD}	1.5		3.0	V	50 Ω ≤ R_L ≤ 65 Ω
		1.4		3.3	V	45 Ω ≤ R_L ≤ 70 Ω
		1.5		5.0	V	R_L = 2240 Ω
Standby Mode						STBY high, R_L and C_F open
CANH, CANL Voltage	V_{CANL}, V_{CANH}	−0.1		+0.1	V	
Differential Output Voltage	V_{OD}	−200		+200	mV	
Output Symmetry (V_{ISOIN} − V_{CANH} − V_{CANL})	V_{SYM}	−0.55		+0.55	V	R_L = 60 Ω, C_F = 4.7 nF, RS low
Short-Circuit Current	$\|I_{SC}\|$					R_L open
Absolute						
CANH				115	mA	V_{CANH} = −3 V
CANL				115	mA	V_{CANL} = 18 V
Steady State						
CANH				115	mA	V_{CANH} = −24 V
CANL				115	mA	V_{CANL} = 24 V
Logic Inputs (TXD, SILENT, STBY, AUX_{IN})						
Input Voltage						
High	V_{IH}	0.65 × V_{IO}			V	
Low	V_{IL}			0.35 × V_{IO}	V	
Complementary Metal-Oxide Semiconductor (CMOS) Logic Input Currents	$\|I_{IH}\|$, $\|I_{IL}\|$			10	μA	Input high or low

Parameter	Symbol	Min	Typ	Max	Unit	Test Conditions/Comments
RECEIVER						
Differential Inputs						
Differential Input Voltage Range	V_{ID}					See Figure 28, C_{RXD} open, $-25\ V < V_{CANL}, V_{CANH} < +25\ V$
Recessive		−1.0		+0.5	V	
		−1.0		+0.4	V	STBY high
Dominant		0.9		5.0	V	
		1.15		5.0	V	STBY high
Input Voltage Hysteresis	V_{HYS}		150		mV	
Unpowered Input Leakage Current	$\lvert I_{IN\ (OFF)}\rvert$			10	µA	$V_{CANH}, V_{CANL} = 5\ V, V_{CC} = 0\ V$
Input Resistance						
CANH, CANL	R_{INH}, R_{INL}	6		25	kΩ	
Differential	R_{DIFF}	20		100	kΩ	
Matching	m_R	−0.03		+0.03	Ω/Ω	$m_R = 2 \times (R_{INH} - R_{INL})/(R_{INH} + R_{INL})$
Input Capacitance						
CANH, CANL	C_{INH}, C_{INL}		35		pF	
Differential	C_{DIFF}		12		pF	
Logic Outputs (RXD, AUX_{OUT})						
Output Voltage						
Low	V_{OL}		0.2	0.4	V	Output current (I_{OUT}) = 2 mA
High	V_{OH}					
RXD		$V_{IO} - 0.2$			V	$I_{OUT} = -2$ mA
AUX_{OUT}		+2.4			V	$I_{OUT} = -2$ mA
Short-Circuit Current	I_{OS}					
RXD		7		85	mA	Output voltage (V_{OUT}) = GND_1 or V_{IO}
COMMON-MODE TRANSIENT IMMUNITY[1]						Common-mode voltage (V_{CM}) ≥ 1 kV, transient magnitude ≥ 800 V
Input High, Recessive	$\lvert CM_H\rvert$	75	100		kV/µs	$V_{IN} = V_{IO}$ (AUX_{IN}, TXD) or CANH/CANL recessive
Input Low, Dominant	$\lvert CM_L\rvert$	75	100		kV/µs	$V_{IN} = 0\ V$ (AUX_{IN}, TXD) or CANH/CANL dominant
SLOPE CONTROL						
Input Voltage for Standby Mode	V_{STB}	4.0			V	
Current for Slope Control Mode	I_{SLOPE}			−240	µA	RS voltage (V_{RS}) = 0 V
Slope Control Mode Voltage	V_{SLOPE}	2.1			V	RS current (I_{RS}) = 10 µA
Input Voltage for High Speed Mode	V_{HS}			1	V	

[1] $\lvert CM_H\rvert$ is the maximum common-mode voltage slew rate that can be sustained while maintaining $AUX_{OUT} \geq 2.4$ V, CANH/CANL recessive, or RXD ≥ $V_{IO} - 0.2$ V. $\lvert CM_L\rvert$ is the maximum common-mode voltage slew rate that can be sustained while maintaining $AUX_{OUT} \leq 0.4$ V, CANH/CANL dominant, or RXD ≤ 0.4 V. The common-mode voltage slew rates apply to both rising and falling common-mode voltage edges.

TIMING SPECIFICATIONS

All voltages are relative to their respective ground. 4.5 V ≤ V_{CC} ≤ 5.5 V, 1.7 V ≤ V_{IO} ≤ 5.5 V, −55°C ≤ T_A ≤ +105°C, and STBY low, unless otherwise noted. Typical specifications are at V_{CC} = V_{IO} = 5 V and T_A = 25°C, unless otherwise noted.

Table 2.

Parameter	Symbol	Min	Typ	Max	Unit	Test Conditions/Comments
DRIVER						SILENT low, bit time on the TXD pin as transmitted by the CAN controller (t_{BIT_TXD}) = 200 ns, see Figure 2 and Figure 29, slope resistance (R_{SLOPE}) = 0 Ω, R_L = 60 Ω, load capacitance (C_L) = 100 pF
Maximum Data Rate		12			Mbps	
Propagation Delay from TXD to Bus (Recessive to Dominant)	t_{TXD_DOM}		35	60	ns	
Propagation Delay from TXD to Bus (Dominant to Recessive)	t_{TXD_REC}		46	70	ns	
Transmit Dominant Timeout	t_{DT}	1175		4000	µs	TXD low, see Figure 5
RECEIVER						SILENT low, see Figure 2 and Figure 29, R_L = 60 Ω, C_L = 100 pF, RXD capacitance (C_{RXD}) = 15 pF
Falling Edge Loop Propagation Delay (TXD to RXD)	t_{LOOP_FALL}					
Full Speed Mode				150	ns	R_{SLOPE} = 0 Ω, t_{BIT_TXD} = 200 ns
Slope Control Mode				300	ns	R_{SLOPE} = 47 kΩ, t_{BIT_TXD} = 1 µs
Rising Edge Loop Propagation Delay (TXD to RXD)	t_{LOOP_RISE}					
Full Speed Mode				150	ns	R_{SLOPE} = 0 Ω, t_{BIT_TXD} = 200 ns
Slope Control Mode				300	ns	R_{SLOPE} = 47 kΩ, t_{BIT_TXD} = 1 µs
Loop Delay Symmetry (Minimum Recessive Bit Width)	t_{BIT_RXD}					
2 Mbps		450		550	ns	t_{BIT_TXD} = 500 ns
5 Mbps		160		220	ns	t_{BIT_TXD} = 200 ns
8 Mbps		85		140	ns	t_{BIT_TXD} = 125 ns
12 Mbps		50		91.6	ns	t_{BIT_TXD} = 83.3 ns
CANH, CANL SLEW RATE	|SR|		7		V/µs	SILENT low, see Figure 29, R_L = 60 Ω, C_L = 100 pF, R_{SLOPE} = 47 kΩ
STANDBY MODE						
Minimum Pulse Width Detected (Receiver Filter Time)	t_{FILTER}	1		5	µs	STBY high, see Figure 4
Wake-Up Pattern Detection Reset Time	t_{WUPR}	1175		4000	µs	STBY high, see Figure 4
Normal Mode to Standby Mode Time	t_{STBY_ON}			25	µs	
Standby Mode to Normal Mode Time	t_{STBY_OFF}			25	µs	Time until RXD valid
AUXILIARY SIGNAL						
Maximum Switching Rate	f_{AUX}	20			kHz	
AUX_{IN} to AUX_{OUT} Propagation Delay	t_{AUX}			25	µs	
SILENT MODE						
Normal Mode to Silent Mode Time	t_{SILENT_ON}		40	100	ns	TXD low, R_{SLOPE} = 0 Ω, see Figure 3
Silent Mode to Normal Mode Time	t_{SILENT_OFF}		50	100	ns	TXD low, R_{SLOPE} = 0 Ω, see Figure 3

Timing Diagrams

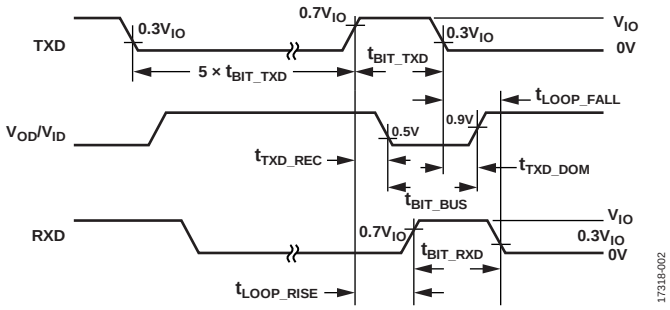


Figure 2. Transceiver Timing Diagram

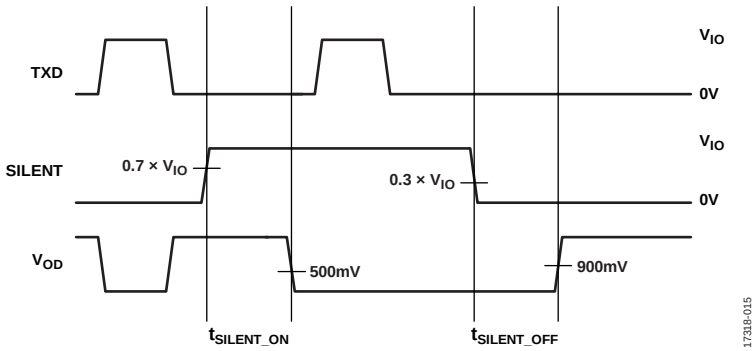


Figure 3. Silent Mode Timing Diagram

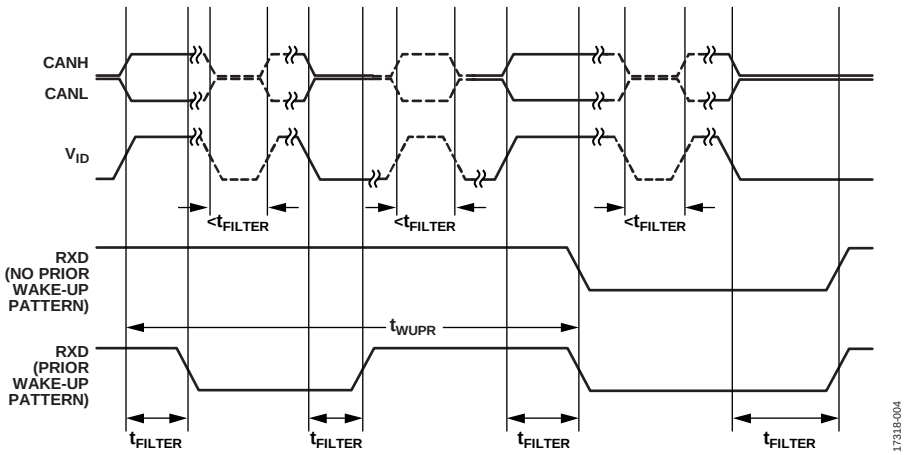


Figure 4. Wake-Up Pattern Detection and Filtered RXD in Standby Mode Timing Diagram

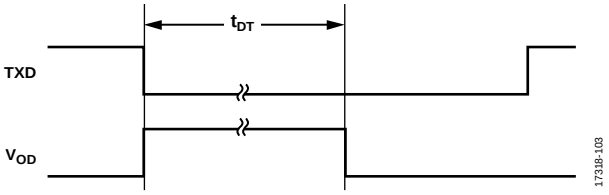


Figure 5. Dominant Timeout

INSULATION AND SAFETY RELATED SPECIFICATIONS

For additional information, see www.analog.com/icouplersafety.

Table 3.

Parameter	Symbol	Value	Unit	Test Conditions/Comments
Rated Dielectric Insulation Voltage		3000	V rms	1-minute duration
Minimum External Air Gap (Clearance)	L (I01)	7.8	mm min	Measured from input terminals to output terminals, shortest distance through air
Minimum External Tracking (Creepage)	L (I02)	7.8	mm min	Measured from input terminals to output terminals, shortest distance path along body
Minimum Clearance in the Plane of the Printed Circuit Board (PCB Clearance)	L (PCB)	7.8	mm min	Measured from input terminals to output terminals, shortest distance through air, line of sight, in the PCB mounting plane
Minimum Internal Gap (Internal Clearance)		21	µm min	Insulation distance through insulation
Tracking Resistance (Comparative Tracking Index)	CTI	>600	V	IEC 60112
Material Group		I		Material Group (IEC 60664-1)

PACKAGE CHARACTERISTICS

Table 4.

Parameter	Symbol	Min	Typ	Max	Unit	Test Conditions/Comments
Resistance (Input to Output)[1]	R_{I-O}		10^{13}		Ω	
Capacitance (Input to Output)[1]	C_{I-O}		3.7		pF	f = 1 MHz
Input Capacitance[2]	C_I		4.0		pF	

[1] The device is considered a 2-terminal device: Pin 1 through Pin 10 are shorted together, and Pin 11 through Pin 20 are shorted together.
[2] Input capacitance is from any input data pin to ground.

REGULATORY INFORMATION

See Table 9 for details regarding maximum working voltages for specific cross isolation waveforms and insulation levels. The ADM3057E-EP is approved or pending approval by the organizations listed in Table 5.

Table 5.

UL (Pending)[1]	CSA (Pending)	VDE (Pending)[2]	CQC (Pending)
Recognized Under UL 1577 Component Recognition Program Single Protection, 3000 V rms Isolation Voltage	Approved under CSA Component Acceptance Notice 5A CSA 60950-1-07+A1+A2 and IEC 60950-1, second edition, +A1+A2 Basic insulation at 780 V rms (1103 V_{PEAK}) Reinforced insulation at 390 V rms (552 V_{PEAK}) IEC 60601-1 Edition 3.1: Basic insulation (1 MOPP), 490 V rms (693 V_{PEAK}) Reinforced insulation (2 MOPP), 250 V rms (353 V_{PEAK}) CSA 61010-1-12 and IEC 61010-1 third edition Basic insulation at 300 V rms mains, 780 V secondary (1103 V_{PEAK}) Reinforced insulation at 300 V rms mains, 390 V secondary (552 V_{PEAK})	DIN V VDE V 0884-10 (VDE V 0884-10):2006-12 Reinforced insulation 849 V_{PEAK}, surge isolation voltage (V_{IOTM}) = 6000 V_{PEAK}	Certified under CQC11-471543-2012 GB4943.1-2011: basic insulation at 780 V rms (1103 V_{PEAK}) Reinforced insulation at 390 V rms (552 V_{PEAK})
File E214100	File 205078	File 2471900-4880-0001	File (pending)

[1] In accordance with UL 1577, each ADM3057E-EP is proof tested by applying an insulation test voltage ≥ 3600 V rms for 1 sec.
[2] In accordance with DIN V VDE V 0884-10, each ADM3057E-EP is proof tested by applying an insulation test voltage ≥ 1592 V_{PEAK} for 1 sec (partial discharge detection limit = 5 pC). The * marking branded on the component designates DIN V VDE V 0884-10 approval.

DIN V VDE V 0884-10 (VDE V 0884-10) INSULATION CHARACTERISTICS

These isolators are suitable for reinforced electrical isolation only within the safety limit data. The protective circuits ensure the maintenance of the safety data. The asterisk (*) marking on packages denotes DIN V VDE V 0884-10 approval.

Table 6. VDE Characteristics

Description	Test Conditions/Comments	Symbol	Characteristic	Unit
Installation Classification per DIN VDE 0110				
For Rated Mains Voltage ≤ 150 V rms			I to IV	
For Rated Mains Voltage ≤ 300 V rms			I to IV	
For Rated Mains Voltage ≤ 400 V rms			I to III	
Climatic Classification			55/105/21	
Pollution Degree per DIN VDE 0110, Table 1			2	
Maximum Working Insulation Voltage		V_{IORM}	849	V_{PEAK}
Input to Output Test Voltage, Method B1	$V_{IORM} \times 1.875 = V_{PR}$, 100% production test, t_m = 1 sec, partial discharge < 5 pC	$V_{pd(m)}$	1592	V_{PEAK}
Input to Output Test Voltage, Method A				
After Environmental Tests Subgroup 1	$V_{IORM} \times 1.5 = V_{pd(m)}$, t_{ini} = 60 sec, t_m = 10 sec, partial discharge < 5 pC	$V_{pd(m)}$	1273	V_{PEAK}
After Input or Safety Test Subgroup 2 and Subgroup 3	$V_{IORM} \times 1.2 = V_{pd(m)}$, t_{ini} = 60 sec, t_m = 10 sec, partial discharge < 5 pC	$V_{pd(m)}$	1018	V_{PEAK}
Highest Allowable Overvoltage	Transient overvoltage, t_{TR} = 10 sec	V_{IOTM}	6000	V_{PEAK}
Surge Isolation Voltage Reinforced	$V_{IOSM(TEST)}$ = 10 kV, 1.2 µs rise time, 50 µs, 50% fall time	V_{IOSM}	6000	V_{PEAK}
Safety Limiting Values	Maximum value allowed in the event of a failure (see Figure 6)			
Case Temperature		T_S	150	°C
Total Power Dissipation at 25°C		P_S	2.35	W
Insulation Resistance at T_S	V_{IO} = 500 V	R_S	$>10^9$	Ω

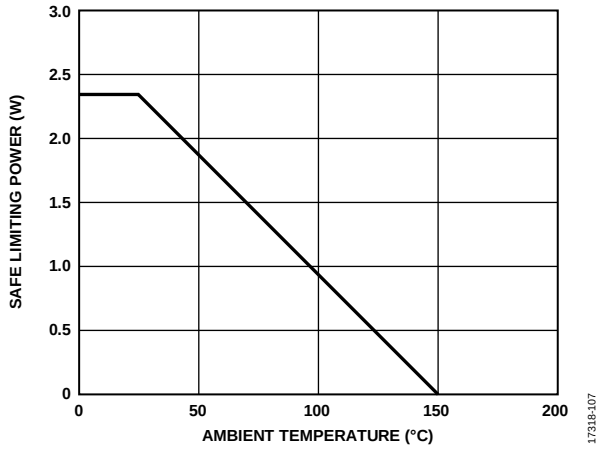


Figure 6. Thermal Derating Curve, Dependence of Safety Limiting Values with Ambient Temperature per DIN V VDE V 0884-10

ABSOLUTE MAXIMUM RATINGS

Pin voltages with respect to GND_x are on the same side, unless otherwise noted.

Table 7.

Parameter	Rating
V_{CC}	−0.5 V to +6 V
V_{IO}	−0.5 V to +6 V
Logic Side Input/Output: TXD, RXD, AUX_{IN}, SILENT, STBY	−0.5 V to V_{IO} + 0.5 V
CANH, CANL	−40 V to +40 V
AUX_{OUT}, RS	−0.5 V to V_{ISOIN} + 0.5 V
Operating Temperature Range	−55°C to +105°C
Storage Temperature Range	−65°C to +150°C
Junction Temperature (T_J Maximum)	150°C
Power Dissipation	(T_J maximum − T_A)/θ_{JA}
Electrostatic Discharge (ESD)	
IEC 61000-4-2, CANH/CANL	
Across Isolation Barrier to GND_1	±8 kV
Contact Discharge to GND_2	±8 kV
Air Discharge to GND_2	±15 kV
Human Body Model (HBM), All Pins, 1.5 kΩ, 100 pF	4 kV
Moisture Sensitivity Level (MSL)	MSL3

Stresses at or above those listed under Absolute Maximum Ratings may cause permanent damage to the product. This is a stress rating only; functional operation of the product at these or any other conditions above those indicated in the operational section of this specification is not implied. Operation beyond the maximum operating conditions for extended periods may affect product reliability.

THERMAL RESISTANCE

Thermal performance is directly linked to PCB design and operating environment. Careful attention to PCB thermal design is required.

The thermal resistance value specified in Table 8 is simulated based on JEDEC specifications (unless specified otherwise) and must be used in compliance with JESD51-12.

Table 8. Thermal Resistance

Package Type	θ_{JA}	Unit
RW-20[1]	53	°C/W

[1] The θ_{JA} value is based on simulations of a devices mounted on a JEDEC standard, 4-layer board with fine width traces and still air. See the ADM3057E data sheet for thermal model definitions.

ESD CAUTION

ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

Table 9. Maximum Continuous Working Voltage[1]

Parameter	Rating	Unit	Constraint
AC Voltage			
Bipolar Waveform			
Basic Insulation	566	V_{PEAK}	Lifetime limited by insulation lifetime per VDE-0884-11
Reinforced Insulation	467	V_{PEAK}	Lifetime limited by insulation lifetime per VDE-0884-11
Unipolar Waveform			
Basic Insulation	1131	V_{PEAK}	Lifetime limited by insulation lifetime per VDE-0884-11
Reinforced Insulation	933	V_{PEAK}	Lifetime limited by insulation lifetime per VDE-0884-11
DC Voltage			
Basic Insulation	1560	V_{PEAK}	Lifetime limited by package creepage per IEC 60664-1
Reinforced Insulation	780	V_{PEAK}	Lifetime limited by package creepage per IEC 60664-1

[1] Maximum continuous working voltage refers to the continuous voltage magnitude imposed across the isolation barrier. See the ADM3057E data sheet for more details.

PIN CONFIGURATION AND FUNCTION DESCRIPTIONS

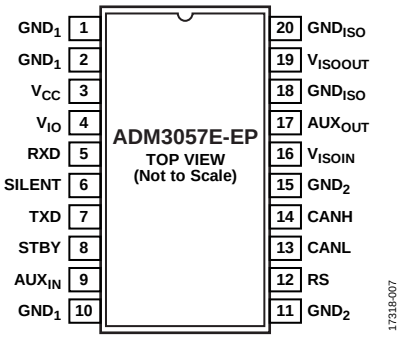


Figure 7. Pin Configuration

Table 10. Pin Function Descriptions

Pin No.	Mnemonic	Description
1, 2, 10	GND_1	Ground, Logic Side.
3	V_{CC}	*iso*Power Power Supply, 4.5 V to 5.5 V. This pin requires 0.1 µF and 10 µF decoupling capacitors.
4	V_{IO}	*i*Coupler Power Supply, 1.7 V to 5.5 V. This pin requires 0.01 µF and 0.1 µF decoupling capacitors.
5	RXD	Receiver Output Data.
6	SILENT	Silent Mode Select with Input High. Bring this input low or leave the pin unconnected (internal pull-down) for normal mode.
7	TXD	Driver Input Data. This pin has a weak internal pull-up resistor to V_{IO}.
8	STBY	Standby Mode Select with Input High. Bring this input low or leave the pin unconnected (internal pull-down) for normal mode.
9	AUX_{IN}	Auxiliary Channel Input. This pin sets the AUX_{OUT} output.
11, 15	GND_2	Ground, Bus Side.
12	RS	Slope Control Pin. Short this pin to ground for full speed operation or use a weak pull-down resistor (for example, 47 kΩ) for slope control mode. An input high signal places the CAN transceiver in standby mode.
13	CANL	CAN Low Input/Output.
14	CANH	CAN High Input/Output.
16	V_{ISOIN}	Isolated Power Supply Input for the CAN Transceiver Bus Side Digital Isolator. This pin requires 0.01 µF and 0.1 µF decoupling capacitors.
17	AUX_{OUT}	Isolated Auxiliary Channel Output. The state of AUX_{OUT} is latched when STBY is high. By default, AUX_{OUT} is low at startup or when V_{IO} is unpowered.
18, 20	GND_{ISO}	Ground for the Isolated DC-to-DC Converter. Connect these pins together through one ferrite bead to PCB ground (bus side).
19	V_{ISOOUT}	Isolated Power Supply Output. This pin requires 0.22 µF and 10 µF capacitors to GND_{ISO}. Connect this pin through a ferrite bead and short the PCB trace to V_{ISOIN} for operation.

OPERATIONAL TRUTH TABLE

Table 11. Truth Table

Power		Inputs[1, 2]						Outputs[2]		Input/Output
V_{CC}	V_{IO}	TXD	SILENT	STBY	AUX_{IN}	RS	Mode	RXD[3]	AUX_{OUT}	CANH/CANL
On	On	Low	Low	Low	Low	Low/ pull-down	Normal/ slope mode	Low	Low	Dominant[4]
On	On	Low	Low	Low	High	Low/ pull-down	Normal/ slope mode	Low	High	Dominant[4]
On	On	High	Low	Low	Low	Low/ pull-down	Normal/ slope mode	High/per bus	Low	Recessive/set by bus
On	On	High	Low	Low	High	Low/ pull-down	Normal/ slope mode	High/per bus	High	Recessive/set by bus
On	On	X	High	Low	Low	X	Listen only	High/per bus	Low	Recessive/set by bus
On	On	X	High	Low	High	X	Listen only	High/per bus	High	Recessive/set by bus
On	On	X	X	High	X	X	Standby	High/WUP/filtered	Last state	Bias to GND_2/set by bus
On	On	X	X	X	Low	Pull-up	Standby[5]	High/WUP/filtered	Low	Bias to GND_2/set by bus
On	On	X	X	X	High	Pull-up	Standby[5]	High/WUP/filtered	High	Bias to GND_2/set by bus
On	Off	Z	Z	Z	Z	Low/ pull-down	Normal/ slope mode	Z	Low	Recessive/set by bus
Off	On	X	X	X	X	X	Transceiver off	High	Z	High impedance/set by bus
Off	Off	Z	Z	Z	Z	Z	Transceiver off	Z	Z	High impedance/set by bus

[1] X means irrelevant.
[2] Z means high impedance within one diode drop of ground.
[3] WUP means remote wake-up pattern.
[4] Limited by t_{DT}.
[5] RS can only set the transceiver to standby mode. RS does not control the digital isolator.

TYPICAL PERFORMANCE CHARACTERISTICS

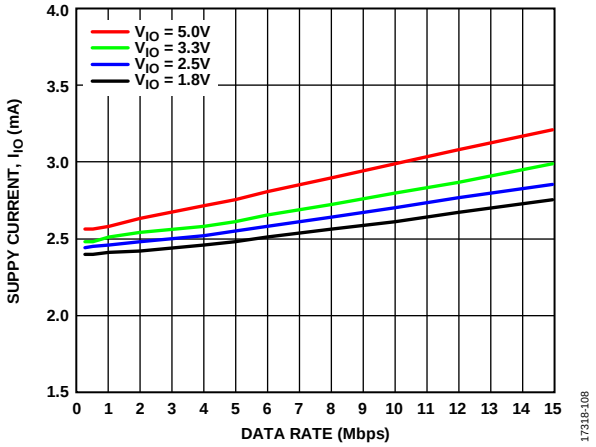


Figure 8. Supply Current, I_{IO} vs. Data Rate

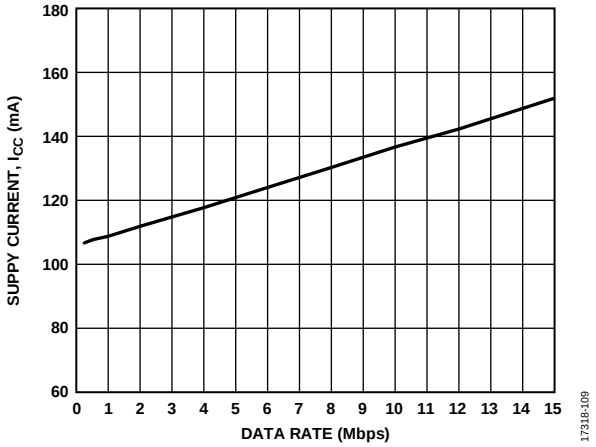


Figure 9. Supply Current, I_{CC} vs. Data Rate

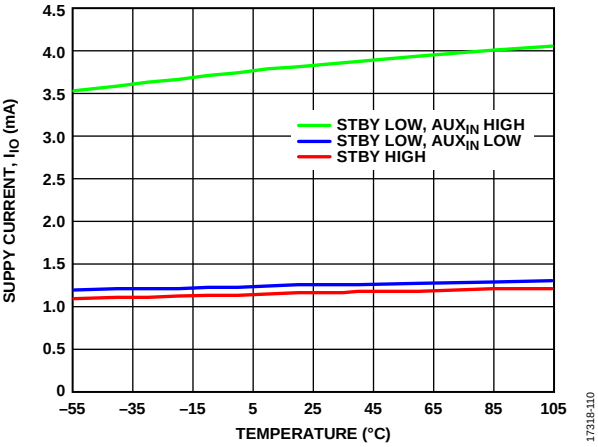


Figure 10. Supply Current, I_{IO} vs. Temperature (Inputs Idle)

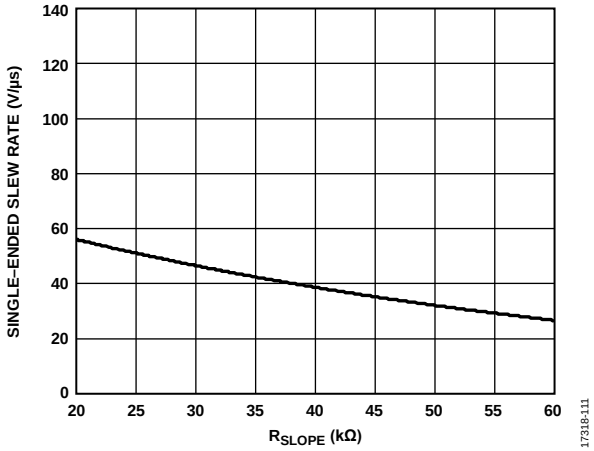


Figure 11. Single-Ended Slew Rate vs. R_{SLOPE}

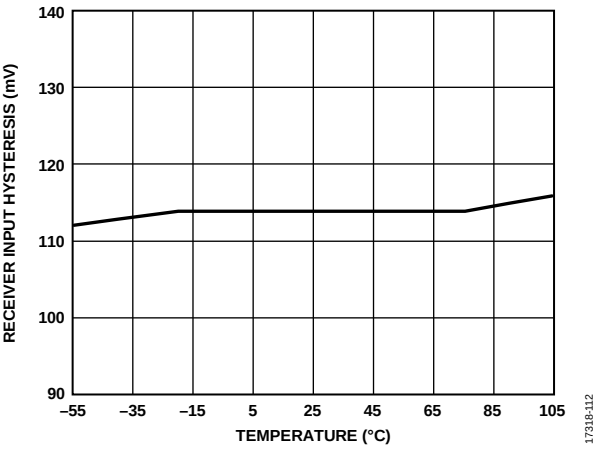


Figure 12. Receiver Input Hysteresis vs. Temperature

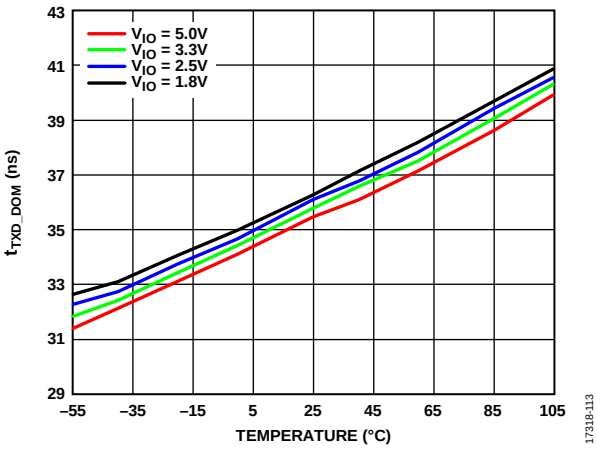


Figure 13. t_{TXD_DOM} vs. Temperature

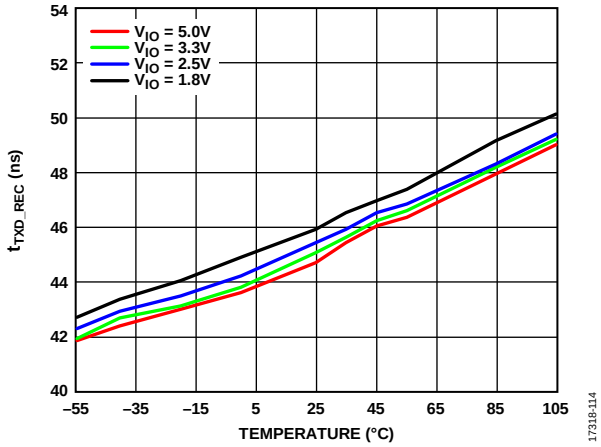


Figure 14. t_{TXD_REC} vs. Temperature

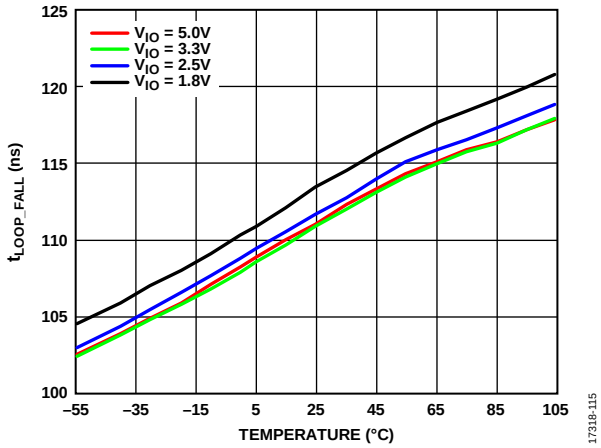


Figure 15. t_{LOOP_FALL} vs. Temperature (R_{SLOPE} = 0 Ω)

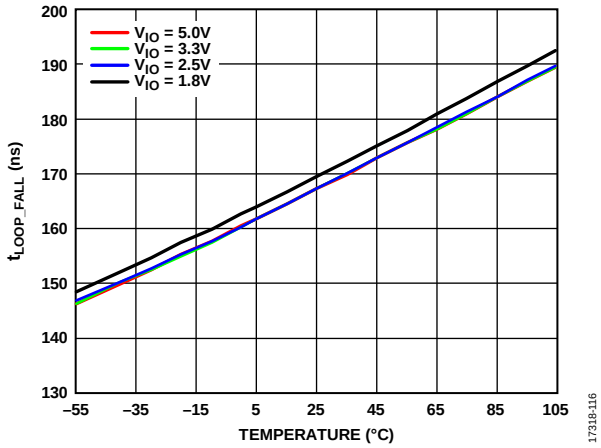


Figure 16. t_{LOOP_FALL} vs. Temperature (R_{SLOPE} = 47 kΩ)

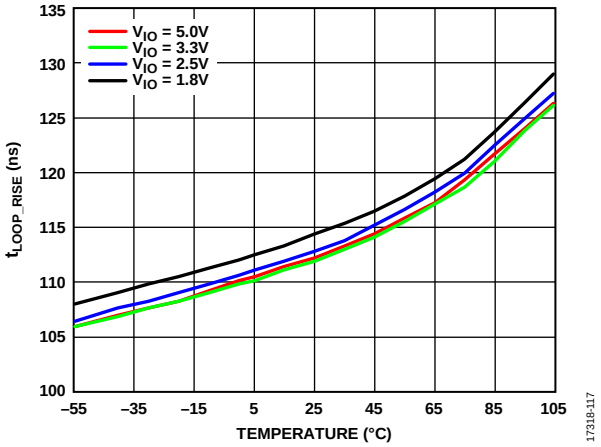


Figure 17. t_{LOOP_RISE} vs. Temperature (R_{SLOPE} = 0 Ω)

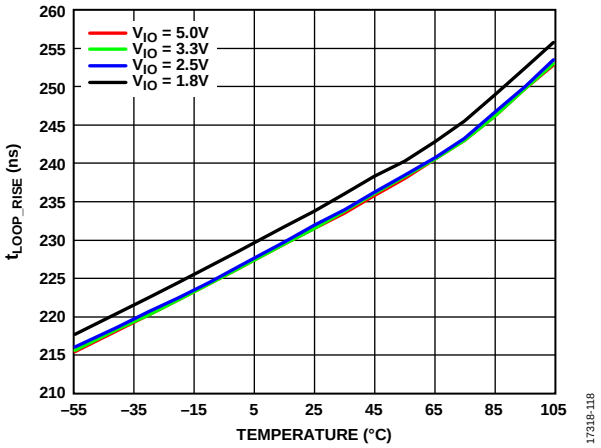


Figure 18. t_{LOOP_RISE} vs. Temperature (R_{SLOPE} = 47 kΩ)

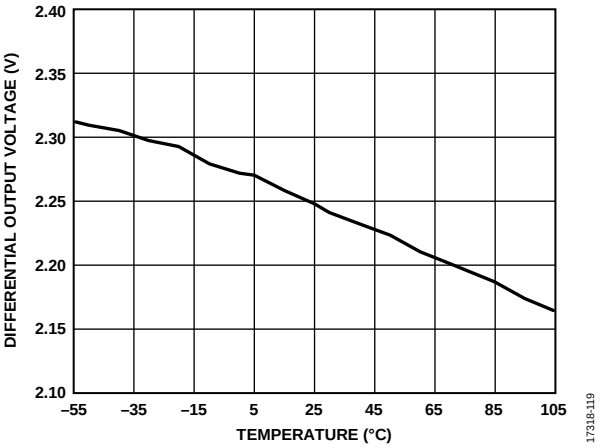


Figure 19. Differential Output Voltage (V_{OD}) vs. Temperature

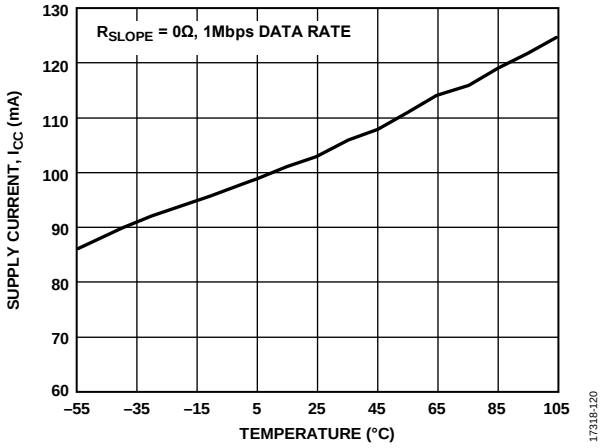


Figure 20. Supply Current, I_{CC} vs. Temperature

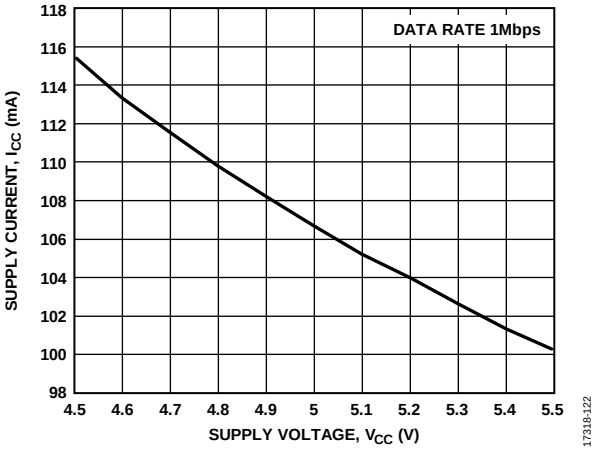


Figure 22. Supply Current, I_{CC} vs. Supply Voltage, V_{CC}, RS = 0 Ω, 1 Mbps

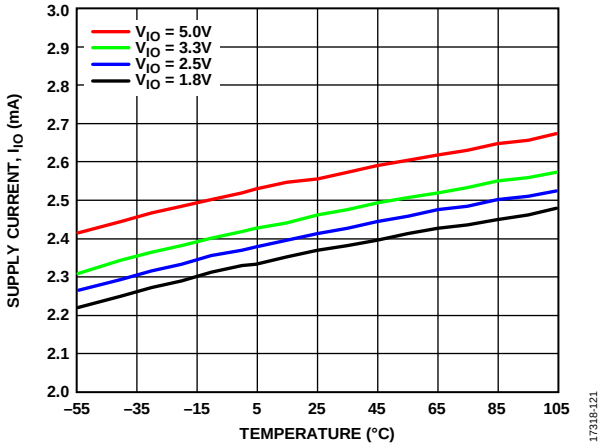


Figure 21. Supply Current, I_{IO} vs. Temperature, RS = 0 Ω, 1 Mbps

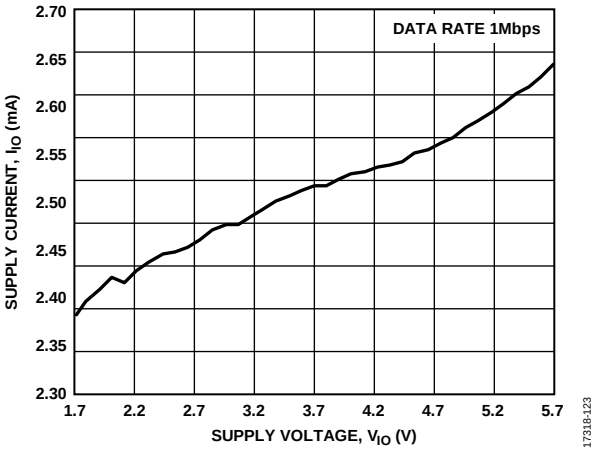


Figure 23. Supply Current, I_{IO} vs. Supply Voltage, V_{IO}, Data Rate = 1 Mbps

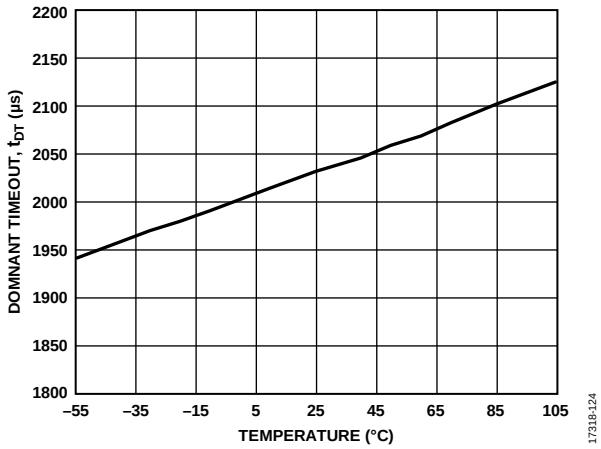


Figure 24. Dominant Timeout, t_{DT} vs. Temperature

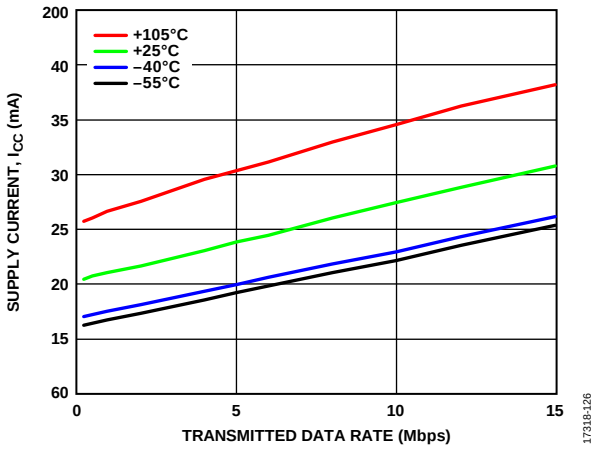


Figure 26. Supply Current, I_{CC} vs. Transmitted Data Rate

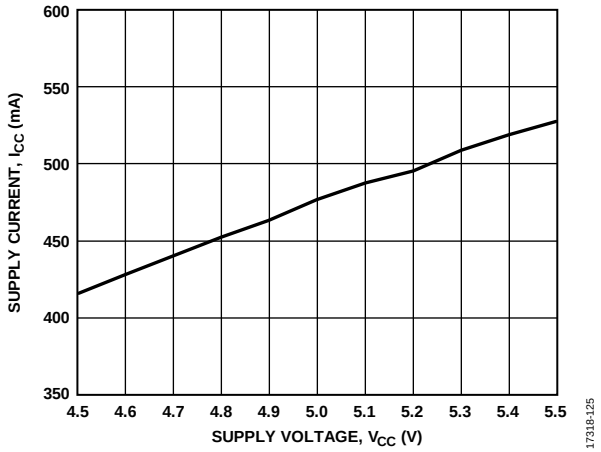


Figure 25. Supply Current, I_{CC} vs. Supply Voltage, V_{CC} (V_{ISOOUT} Shorted to GND_{ISO})

TEST CIRCUITS

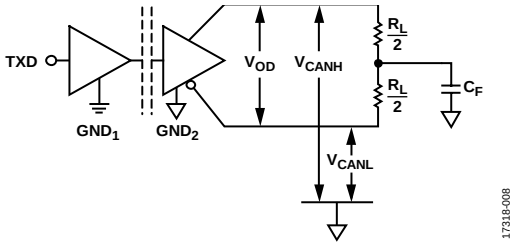


Figure 27. Driver Voltage Measurement

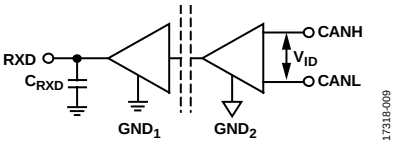
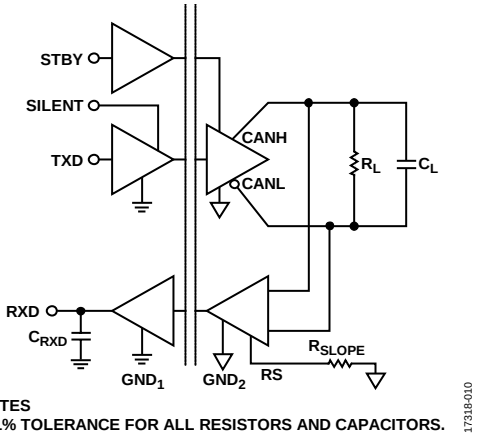


Figure 28. Receiver Voltage Measurement



NOTES
1. 1% TOLERANCE FOR ALL RESISTORS AND CAPACITORS.

Figure 29. Switching Characteristics Measurements

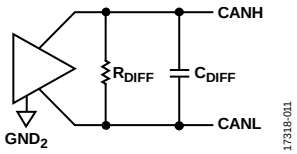


Figure 30. R_{DIFF} and C_{DIFF} Measured in Recessive State, Bus Disconnected

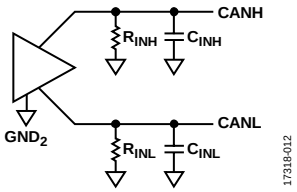
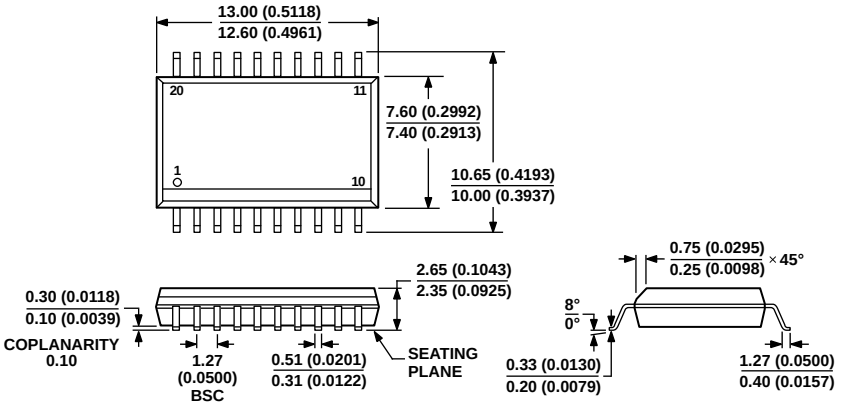


Figure 31. R_{INx} and C_{INx} Measured in Recessive State, Bus Disconnected

OUTLINE DIMENSIONS



COMPLIANT TO JEDEC STANDARDS MS-013-AC
CONTROLLING DIMENSIONS ARE IN MILLIMETERS; INCH DIMENSIONS
(IN PARENTHESES) ARE ROUNDED-OFF MILLIMETER EQUIVALENTS FOR
REFERENCE ONLY AND ARE NOT APPROPRIATE FOR USE IN DESIGN.

06-07-2006-A

Figure 32. 20-Lead Standard Small Outline Package [SOIC_W]
Wide Body
(RW-20)
Dimensions shown in millimeters and (inches)

ORDERING GUIDE

Model[1, 2]	Temperature Range	Package Description	Package Option
ADM3057ETRWZ-EP	−55°C to +105°C	20-Lead Standard Small Outline Package [SOIC_W]	RW-20
ADM3057ETRWZ-EP-RL	−55°C to +105°C	20-Lead Standard Small Outline Package [SOIC_W]	RW-20
EVAL-ADM3055EEBZ		ADM3055E Evaluation Board	

[1] Z = RoHS Compliant Part.
[2] Use the EVAL-ADM3055EEBZ evaluation board to evaluate the ADM3057E-EP.